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PATENT  
YOR920030206US1

## IN THE UNITED STATES PATENT &amp; TRADEMARK OFFICE

In re Application of	:	Larry Shungwei Mok
Serial Number	:	10/784,624
Filing Date	:	02/23/2004
Examiner	:	Tho V. Duong
Group Art Unit	:	3753
For	:	HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

Honorable Commissioner of Patents and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated December 22, 2008, please amend the above-identified application as follows:

In the Claims:

Cancel Claim 2 and amend Claim 1 as set forth in the Appendix attached hereto.

## REMARKS

The Examiner has rejected Claim 1 under 35 U.S.C. §112 second paragraph. In Claim 1, Applicant has revised the wording in the Claim to make it more definite and eliminate the lack of antecedent basis referred to by the Examiner.